



501.37215VC3

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of :
Y. MIYAKE, et al. : Art Unit: 2824
Serial No.: 10/777,084 :
Filed: February 13, 2004 : Examiner: Christian D. Wilson
Confirmation No.: 4121

For: PLASTIC MOLDED TYPE SEMICONDUCTOR DEVICE AND FABRICATION
PROCESS THEREOF

FEE TRANSMITTAL**Mail Stop: AMENDMENT - FEE**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

April 11, 2005

Sir:

Transmitted herewith is an Amendment in the above-identified application.☐ No additional fee is required.☒ Also attached: Credit Card Payment Form; Petition for Extension of Time (One-month)

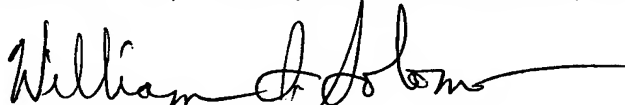
The fee (if applicable) has been calculated as shown below:

	NO. OF CLAIMS	HIGHEST PREVIOUSLY PAID FOR	EXTRA CLAIMS	RATE	FEE
Total Claims	22	21	1	x \$50 =	\$0
Independent Claims	5	5	0	x \$200 =	\$0
TOTAL FEE DUE					\$0

- [X] A Credit Card Payment form in the amount of \$120.00 is attached.
- [X] Commissioner is hereby authorized to charge any additional fees associated with this communication or credit any overpayment, to Deposit Account No. 01-2135, including any filing fees under 37 CFR 1.16 for presentation of extra claims and any patent application processing fees under 37 CFR 1.17.

Respectfully Submitted,

ANTONELLI, TERRY, STOUT & KRAUS, LLP

A handwritten signature in black ink, appearing to read "William I. Solomon", is written over a horizontal line.

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